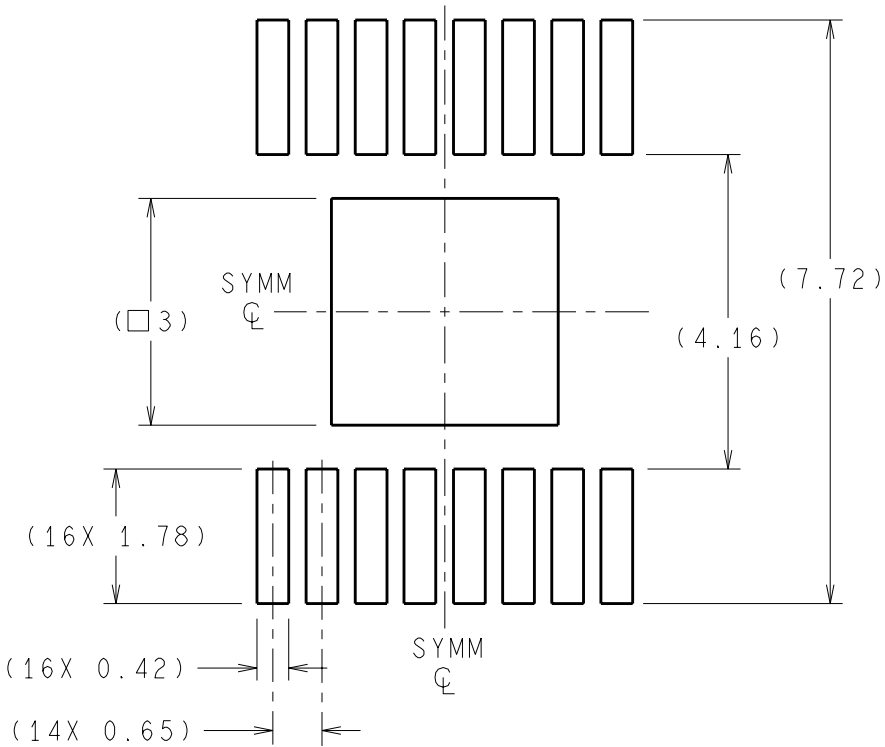
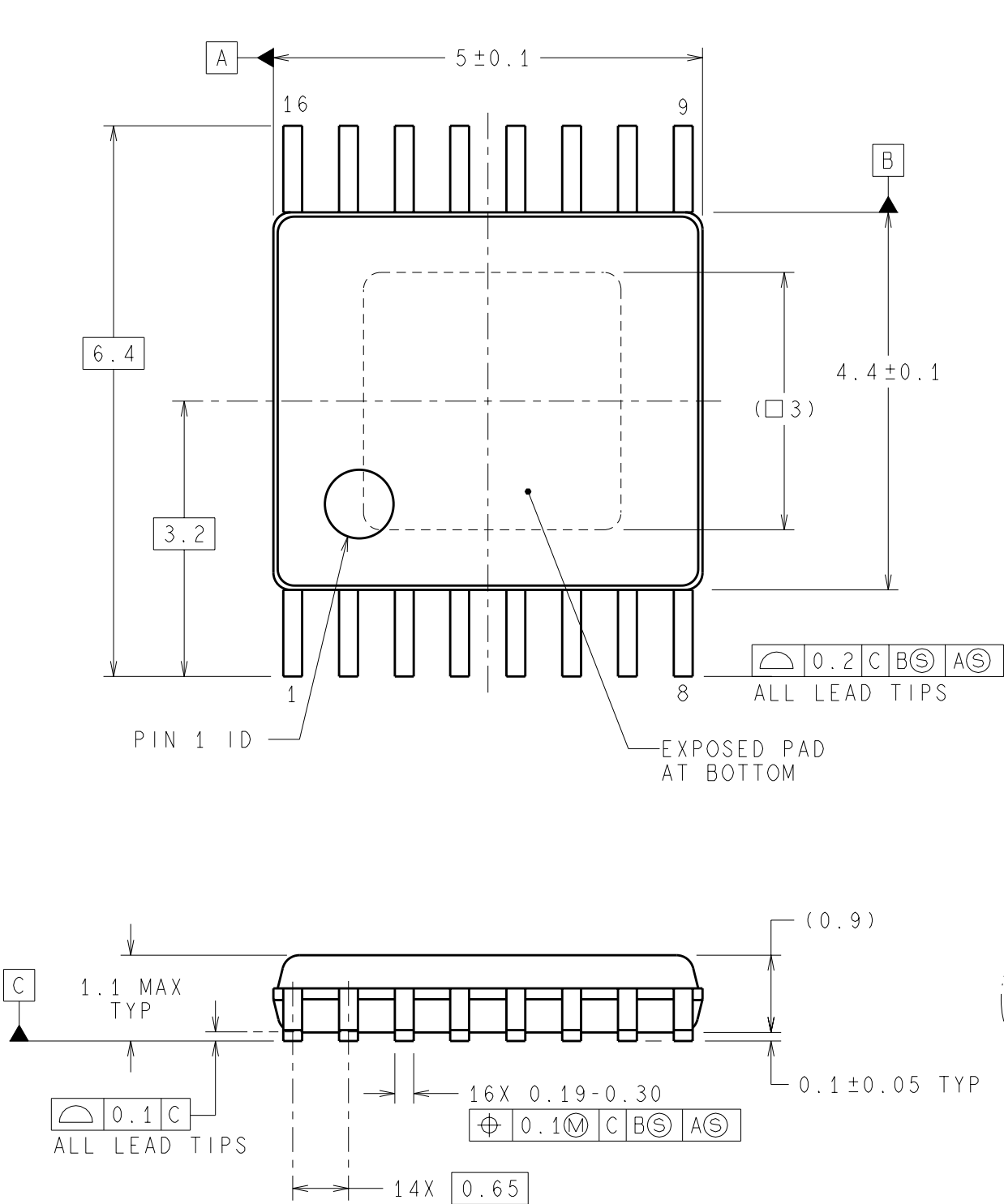
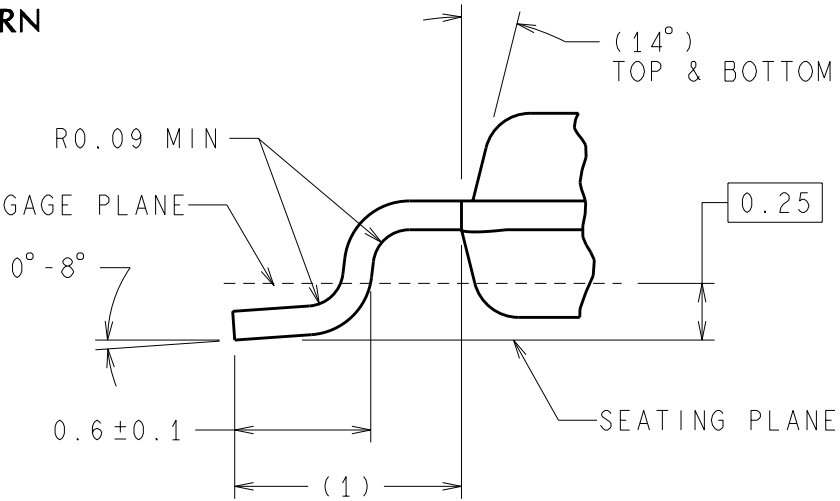
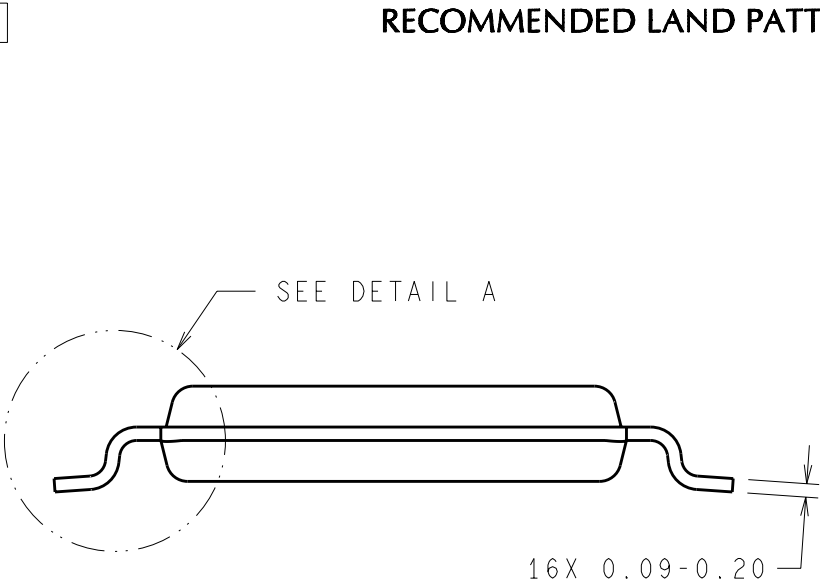


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	986	04/28/2003	TL/RW



RECOMMENDED LAND PATTERN



DETAIL A
TYPICAL

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- REFERENCE JEDEC REGISTRATION MO-153, VARIATION ABT.

APPROVALS		DATE	National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	T. LEQUANG	04/28/2003		
DFTG. CHK.	MARTA SUCHY	04/28/2003	MOLDED TSSOP, JEDEC, EXP PAD, 5.0x4.4x0.9mm BODY, 16 LD, 0.65mm PITCH	
ENGR. CHK.	RANDALL WALBERG	04/28/2003		
PROJECTION		SCALE	SIZE	DRAWING NUMBER
 MM		NTS	B	(SC)MKT-MXA16A
FORMERLY: N/A			SHEET 1 of 1	